

PCN Number: SM040317 Chgnot.doc rev 13 1/14

#### **Product/Process Change Notification (PCN)**

**Customer: Digi-Key** 

Date: 04/03/2017

Customer Part # and/or Lot# affected: A4407KLPTR-T

**Originator: Scott Mitti** 

Phone: 508-854-5627

Duration of Change:	Permanent X Temporary (explain)
<b>Summary description of change</b> : Part Change:	Process Change: X Other:

- 1. Allegro currently manufactures the A4407KLPTR-T at wafer fab, Polar Semiconductor LLC (PSL), Bloomington, MN, USA, utilizing 8" ABCD5 technology. Allegro will be changing wafer fab manufacturing to the 8" ABCD5 technology wafer line at United Microelectronics Corporation (UMC), Hsinshu, Taiwan.
- 2. Allegro will permanently close its wafer probe operations in Worcester, Massachusetts, USA by March 31, 2018. Wafer probe operations will be moved to Allegro MicroSystems Philippines, Inc. (AMPI) located in Manila, Philippines for the part numbers listed in this PCN.
- 3. The above listed device will have an additional final test location: Allegro MicroSystems (Thailand) Co., Ltd. (AMTC).

## What is the part or process changing from (provide details)?

- 1. Allegro currently manufactures the A4407KLPTR-T at wafer fab, Polar Semiconductor LLC (PSL), Bloomington, MN, USA, utilizing 8" ABCD5 technology.
- 2. Currently the device listed is probed in Allegro's Worcester facility.
- 3. In addition to the current Allegro MicroSystems, test facility location in Manila Philippines, a second test facility referred to as Allegro MicroSystems (Thailand) Co., Ltd. (AMTC) located in Saraburi, Thailand will be added as a primary site.a second test facility referred to as Allegro MicroSystems (Thailand) Co., Ltd. (AMTC). Saraburi, Thailand will be added as a primary site.

# What is the part or process changing to (describe the anticipated impact of this change on form, fit and/or function)?

- 1. Allegro will be changing wafer fab manufacturing to the 8" ABCD5 technology wafer line at United Microelectronics Corporation (UMC), Hsinshu, Taiwan.
- 2. Probe location for the listed device(s) will be moved to AMPI. Allegro is utilizing the same probe equipment, test programs and test methodologies in its Philippine facility as is currently being performed in its US facility. Relocation of probe operations reduces movement of wafers between factories shortening overall cycle time and minimizing





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waferhandling. All expansions of probe capability and capacity will now occur at AMPI to support Allegro's future business growth.

- 3. Allegro will be expanding its manufacturing capabilities with the addition of a new, whollyowned integrated circuit test facility located in Saraburi, Thailand. The same make and model test equipment will be utilized and test site transfer buy off data will be on file for each device before production begins.
- Note: Validation of equivalence within a specific application is at the discretion of the Customer

PPAP update r	equire	d?		Yes		No X
reliability testing required? (If Yes, refer to attached plan)				Yes X	No (explain)	
Reliability Qualifica Device: 4407 (94407 Assy Lot #: 1626625 Number of Leads: 24 Tab Location: UMC	1)	esults		Package: LP (eTSSOP) Assembly Location: Unisem Lead Finish: 100% Sn Tracking Number: 3614		
Reason for Qualification	4407	(04407	71) - 2.2 MHz C	onstant On-Time Buck Regulat	or with	Two External
and Two Internal Lin	ear Reg			onstant On-Time Buck Regulat valification Results		
	ear Reg					Two External Requirements Results
and Two Internal Lin 4407 (944071), STR#	ar Reg	ulators	Reliability Qu	Test Conditions 85°C/60% RH, 168 hrs, Peak Reflow=260°C; MSL2, (HAST, AC,	F	Requirements
and Two Internal Lin 4407 (944071), STR# Stress Test	3614 Abv.	Test #	Reliability Qu Test Method JESD22-A113 /	Test Conditions	s.s.	Reguirements Results
and Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning	3614 Abv. PC	Test # A1	Reliability Qu Test Method JESD22-A113 / J-STD-020	Test Conditions   85°C/60% RH, 168 hrs, Peak   Reflow=260°C; MSL2, (HAST, AC, TC)   Ta=130°C, 2 ATM, 85% RH,	5.S. 231	Requirements Results 0 Rejects
And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST	ar Reg	Test # A1 A2	Reliability Qu Test Method JESD22-A113 / J-STD-020 JESD22-A110	Test Conditions   85°C/60% RH, 168 hrs, Peak   Reflow=260°C; MSL2, (HAST, AC, TC)   Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs   Ta=12°C, 100% RH, 15 psig,	5.5. 231 77	Reguirements Results O Rejects O Rejects
And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave	ar Reg	Test # A1 A2 A3	Reliability Qu Test Method JESD22-A113 / J-STD-020 JESD22-A110 JESD22-A102	Test Conditions   S5°C/60% RH, 168 hrs, Peak   Reflow=260°C; MSL2, (HAST, AC, TC)   Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs   Ta=121°C, 100% RH, 15 psig, 0, 96 hrs   Ta = -65°C to +175°C,	5.5. 231 77 77	Reguirements Results 0 Rejects 0 Rejects 0 Rejects
And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature	ar Reg	Test # A1 A2 A3 A4	Reliability Que Test Method JESD22-A113 / J-STD-020 JESD22-A110 JESD22-A102 JESD22-A104	Test Conditions   SS°C/60% RH, 168 hrs, Peak   Reflow=260°C; MSL2, (HAST, AC, TC)   Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs   Ta=121°C, 100% RH, 15 psig, 0, 96 hrs   Ta=21°C, 100% RH, 15 psig, 0, 96 hrs   Ta = -65°C to +175°C, 0, 500, 1000 Cycles   Ta = 125°C,	5.5. 231 77 77 77 77	Requirements Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects
And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature	Abv. PC HAST AC TC HTOL	Test # A1 A2 A3 A4 B1	Reliability Que Test Method JESD22-A113 / J-STD-020 JESD22-A100 JESD22-A102 JESD22-A104 JESD22-A108 JESD22-A108 AEC-Q100-008 / JESD22-A108	Test Conditions   85°C/60% RH, 168 hrs, Peak   Reflow=260°C; MSL2, (HAST, AC, TC)   Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs   Ta=12°C, 100% RH, 15 psig, 0, 96 hrs   Ta=-65°C to +175°C, 0, 500, 1000 Cycles   Ta=125°C, 0, 1000 hrs   Ta=150°C, 0, 48 hrs	231 231 77 77 77 77 77 77 800	Reguirements Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects
And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature Reverse Bias Life Test	Abv. PC HAST AC TC HTOL HTRB	Test # A1 A2 A3 A4 B1 B1	Reliability Qu   Test Method   JESD22-A113 / J-STD-020   JESD22-A102   JESD22-A102   JESD22-A104   JESD22-A108   JESD22-A108   AEC-Q100-008	Test Conditions   85°C/60% RH, 168 hrs, Peak   Reflow=260°C; MSL2, (HAST, AC, TC)   Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs   Ta=12°C, 100% RH, 15 psig, 0, 96 hrs   Ta = -65°C to +175°C, 0, 500, 1000 Cycles   Ta = 125°C, 0, 1000 hrs   Ta = 150°C, 0, 1000 hrs	F   S.S.   231   77   77   77   77   800	Reguirements Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects
And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature Reverse Bias Life Test Early Life Failure Rate	Abv. PC HAST AC TC HTOL HTRB ELFR	Test #   A1   A2   A3   A4   B1   B2	Reliability Qu   Test Method   JESD22-A113 / J-STD-020   JESD22-A110   JESD22-A102   JESD22-A104   JESD22-A108   JESD22-A108   JESD22-A108   MEI-Std-883	Test Conditions   S5°C/60% RH, 168 hrs, Peak   Reflow=260°C; MSL2, (HAST, AC, TC)   Ta=130°C, 2 ATM, 85% RH, 0, 96 hrs   Ta=121°C, 100% RH, 15 psig, 0, 96 hrs   Ta=121°C, 100% RH, 15 psig, 0, 96 hrs   Ta== 12°C, 100% RH, 15 psig, 0, 500, 1000 Cycles   Ta== 125°C, 0, 1000 hrs   Ta== 150°C, 0, 48 hrs   Temp conditions and sample size are	F   S.S.   231   77   77   77   77   800	Results Results O Rejects O Rejects O Rejects O Rejects O Rejects O Rejects O Rejects; Ppk>1.67
And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature Reverse Bias Life Test Early Life Failure Rate Wire Bond Pull Electrostatic Discharge Human Body	Abv. 3614 Abv. PC HAST AC TC HTOL HTRB ELFR WBP	Test #   A1   A2   A3   A4   B1   B2   C2	Reliability Question   Test Method   JESD22-A113 / J-STD-020   JESD22-A110   JESD22-A102   JESD22-A102   JESD22-A104   JESD22-A108   JESD22-A108   JESD22-A108   JESD22-A108   MELSD22-A108   MI-Std-883   Method 2011   AEC-Q100-002	Test Conditions   85°C/60% RH, 168 hrs, Peak   Reflow=260°C; MSL2, (HAST, AC, TC)   7a=130°C, 2 ATM, 85% RH, 0, 96 hrs   7a=12°C, 100% RH, 15 psig, 0, 96 hrs   Ta = -65°C to +175°C, 0, 500, 1000 Cycles   Ta = 125°C, 0, 48 hrs   Ta = 150°C, 0, 48 hrs   Temp conditions and sample size are defined in the test method. (after TC   Test Conditions, Sampling Size are defined in the Test Method	231 231 77 77 77 77 77 77 800	Results Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects; 0
And Two Internal Lin 4407 (944071), STR# Stress Test Preconditioning HAST Autoclave Temperature Cycle High Temperature Operating Life High Temperature Reverse Bias Life Test Early Life Failure Rate Wire Bond Pull Electrostatic Discharge Human Body Model(STR#3813)	Abv. PC HAST AC TC HTOL HTRB ELFR WBP HBM	Test #   A1   A2   A3   A4   B1   B2   C2   E2	Reliability Qu   Test Method   JESD22-A113 / J-STD-020   JESD22-A110   JESD22-A102   JESD22-A104   JESD22-A108   JESD22-A108   JESD22-A108   Mil-Std-883   Method 2011   AEC-Q100-002 / JS-001-2014	Test Conditions   SS°C/60% RH, 168 hrs, Peak   Rsflow=260°C; MSL2, (HAST, AC, IC)   Ta=130°C, 2 ATM, 85% RH,   0, 96 hrs   Ta=121°C, 100% RH, 15 psig,   0, 96 hrs   Ta=125°C,   0, 1000 hrs   Ta= 150°C,   0, 48 hrs   Test Conditions, Sampling Size are din the test method   In the Test Method   Test Conditions, Sampling Si	231 231 77 77 77 77 77 77 800	Reguirements Results 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects 0 Rejects; Ppk>1.67 Classification 2 HBM =2.0 kV

This device qualification is considered to be passing all environmental stress evaluations per the Allegro MicroSystems, 900019 specification and AEC-Q100.

Approved by:

<u>Bob Domoro</u> Bob Demers Product Safety and Reliability Allegro MicroSystems, LLC

Allegro MicroSystems, LLC





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### Expected completion date for internal qualification: Complete

### Expected PPAP availability date: N/A

**Target implementation date: December 2017** 

Estimated date of first shipment: January 2018

Expected sample availability date: Available Upon Request

			Date Required:
<b>Customer Approval Required</b>	:		
	No	Х	Notification Only

**Please note:** It is our intention to inform our customer of changes as early as possible. Under Allegro's procedure for product/process change notification, Allegro strives, based on its technical judgment, to provide notification of significant changes that may affect form, fit or function. However, as Allegro cannot ensure evaluation of product/process changes for each and every application; the customer retains responsibility to validate the impact of a change on its application suitability. If samples are needed for validation of a change, requests may be made via the contact information provided herein. Please contact your Account Manager or local Sales contact for any questions. We would kindly request your consideration so we can meet our target date for implementation. Unless both parties agree to extend the implementation date, this change will be implemented as scheduled.

Customer comments/Conditions of Acceptance:

Approved by: Date: cc: Allegro Sales/Marketing/Quality

Title: